



Material Content Data Sheet



Sales Product Name		BSC110N06NS3 G		Issued		20. July 2018		
MA#		MA001510240						
Package		PG-TDSON-8-40		Weight*		118.79 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.296	1.09	1.09	10910	10910
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		318	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	copper	7440-50-8	37.762	31.80	31.84	317884	318297
wire	non noble metal	copper	7440-50-8	0.060	0.05	0.05	505	505
encapsulation	organic material	carbon black	1333-86-4	0.086	0.07		722	
	plastics	epoxy resin	-	6.775	5.70		57036	
	inorganic material	silicondioxide	60676-86-0	36.021	30.32	36.09	303229	360987
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12220	12220
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1393	1393
solder	noble metal	silver	7440-22-4	0.037	0.03		309	
	non noble metal	tin	7440-31-5	0.029	0.02		247	
	non noble metal	lead	7439-92-1	1.404	1.18	1.23	11816	12372
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		95	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
	non noble metal	copper	7440-50-8	11.320	9.53	9.54	95294	95418
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		188	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	copper	7440-50-8	22.292	18.77	18.80	187654	187898
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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